TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN# 20131011003
Qualification of Aizu and JCAP as additional Fab site and Assembly/Test site options for select devices in the CMOS Fab process
Change Notification / Sample Request

Date: 10/16/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20131011003
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LP5521TM/NOPB	LP5521TM NOPB
LP5521TM/NOPB	LP5521TM/NOPB
LP8556TME-E09/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20131011003	**PCN Date:**	10/16/2013

Title:	Qualification of Aizu and JCAP as additional Fab site and Assembly/Test site options for select devices in the CMOS Fab process.

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

***Proposed 1st Ship Date:**	01/16/2014	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the addition of Aizu and JCAP as additional Fab site and Assembly/Test site options for select devices in the CMOS Fab Process in Maine. There are no changes to the Bill of Materials as a result of this change. Change combinations are in 2 groups as shown below:

Group 1: Fab Site

Current Site/Process/Wafer Diameter	Additional Site/Process/Wafer Diameter
MAINEFAB/CMOS7/200mm	AIZU/CMOS7/200mm

Group 2: Assembly and Test Site

TIEM	Assembly Site Origin (22L)	ASO: CU6
JCAP	Assembly Site Origin (22L)	ASO: JCP

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Group 1 (Fab Site):

Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)
MAINEFAB	CUA	USA
AIZU	CU2	JPN

Group 2 (Assembly and Test Site):

TIEM	Assembly Site Origin (22L)	ASO: CU6
JCAP	Assembly Site Origin (22L)	ASO: JCP

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

G4

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO:SHE (21L) CCO:USA
(22L) ASO:MLA (23L) ACO:MYS

Product Affected Group 1 (Fab Site):

LM3639TME/NOPB	LM3639TMX/NOPB

Product Affected Group 2 (Assembly and Test Site):

LM3533TME-40/NOPB	LP8556TME-E09/NOPB	LP8556TMX-E09/S7003056	LP5521TM/NOPB
LM3533TMX-40/NOPB	LP8556TMX-E09/NOPB	LM3639TME/NOPB	LP5521TMX/NOPB
LP5562TME/NOPB	LP8556TMX-E09/S1	LM3639TMX/NOPB	LP5521TMX/S7002954
LP5562TMX/NOPB			

Reference Qualification Data: CMOS7 Process at AIZU/JCAP

Qualification Data: (Approved: 7/26/2013)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qualification Device: LM3564A1TMX (MSL LEVEL1-260C)

Package / Die Attributes

Wafer Fab Site:	AIZU	Assembly Site:	JCAP
Wafer Fab Process:	CMOS7	# Pins-Designator:	20-YFQ
Wafer Diameter:	200mm	Package Family:	WCSP
Metallization:	Al .5%Cu	Bump Composition:	SnAgCu
Passivation:	PECVDOX/NITRIDE	Bump Diameter:	.25mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Life Test	125C (1000 Hrs)	77/0	77/0	77/0
High Temp Storage Bake	150C (1000 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65/125C (500 Cycles)	77/0	77/0	77/0
ESD CDM	500V	3/0	3/0	3/0
ESD HBM	1500V	3/0	3/0	3/0
Latch-up	(per JESD78)	6/0	6/0	6/0

**Preconditioning: MSL1@260C

Reference Qualification Data: CMOS9T Process at AIZU/JCAP

Qualification Data: (Approved: 8/23/2013)			
This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.			
Qualification Device: LP5907UVX2.85 (MSL LEVEL1-260C)			
Package / Die Attributes			
Wafer Fab Site:	AIZU	Assembly Site:	JCAP
Wafer Fab Process:	CMOS9T	# Pins-Designator:	4-YKE
Wafer Diameter:	200mm	Package Family:	YKE
Metallization:	Al .5%Cu	Bump Composition:	SnAgCu
Passivation:	PECVDOX/NITRIDE	Bump Diameter:	.2mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65/125C (500 Cycles)	77/0	77/0	77/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com